PCN Number:	20140411000	PCN Date:	04/22/2014
Title:	Assembly site move to CAR for select devices in the SOIC (DW) package		
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037
Dept:	Quality Services		
Proposed 1st Ship Date:	10/22/2014	Estimated Sample Availability:	Date provided at sample request

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☒	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

Assembly site move to CAR for select devices in the SOIC(DW) package which are currently assembled at CRS. No material differences between assembly sites.

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None.

Changes to product identification resulting from this PCN:

Sample Product Shipping Label (not actual product label)

Assembly Site

Carsem S	Assembly Site Origin (22L)	ASO: CRS
Carsem M	Assembly Site Origin (22L)	ASO: CAR

TEXAS INSTRUMENTS
G4
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR SEAL DT
MSL 1 /235C/UNLIM 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750
(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Assembly Site Code: CRS = W, CAR = V

Product Affected:

UC2909MDWREP	V62/10616-01XE

Qualification Data: Approved 05/03/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Device 1 : UC2849DW (MSL 2-260C)

Package Construction Details

Assembly Site:	CAR	Mold Compound:	438360
# Pins-Designator, Family:	24-DW, SOIC	Mount Compound:	434165
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size Pass/Fail
Electrical Characterization	-	Pass
**Autoclave 121C	121C, 2 atm (96 Hrs)	72/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	72/0
Physical Dimensions	(per mechanical drawing)	Pass
Manufacturability	(Assembly Site)	Pass
**Thermal Shock	-65C/+150C (500 Cyc)	72/0

Notes: ** Preconditioning sequence Level 2-260C

Qual Device 2 : UC3907DW (MSL 2-260C)

Package Construction Details

Assembly Site:	CAR	Mold Compound:	438358
# Pins-Designator, Family:	16-DW, SOIC	Mount Compound:	434165
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size Pass/Fail
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
Physical Dimensions	(per mechanical drawing)	Pass
Manufacturability	(Assembly Site)	Pass
**Thermal Shock	-65C/+150C (500 Cyc)	77/0

Notes: ** Preconditioning sequence Level 2-260C

Qual Device 3 : UCC2750DW (MSL 2-260C)			
Package Construction Details			
Assembly Site:	CAR	Mold Compound:	438360
# Pins-Designator, Family:	28-DW, SOIC	Mount Compound:	434165
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., AU

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size Pass/Fail
Electrical Characterization	-	Pass
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
Physical Dimensions	(per mechanical drawing)	Pass
Manufacturability	(Assembly Site)	Pass
**Thermal Shock	-65C/+150C (500 Cyc)	77/0
Notes: ** Preconditioning sequence Level 2-260C		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com